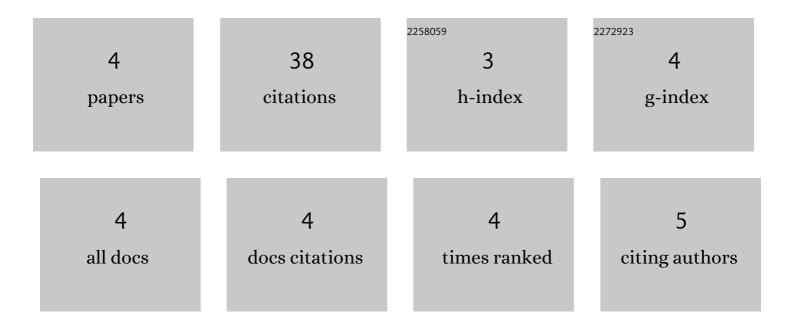
## Mayank Srivastava

List of Publications by Year in descending order

Source: https://exaly.com/author-pdf/5414202/publications.pdf Version: 2024-02-01



#	Article	IF	CITATIONS
1	The influence of ultrasonic vibrations on material removal in the silicon wafer polishing using DDCAMRF: Experimental investigations and process optimization. Proceedings of the Institution of Mechanical Engineering Science, 2022, 236, 3198-3215.	2.1	6
2	Review on the various strategies adopted for the polishing of silicon wafer — A chemical perspective. Materials Today: Proceedings, 2022, 63, 62-68.	1.8	5
3	Experimental investigation into polishing of monocrystalline silicon wafer using double-disc chemical assisted magnetorheological finishing process. Proceedings of the Institution of Mechanical Engineers, Part C: Journal of Mechanical Engineering Science, 2021, 235, 5467-5486.	2.1	9
4	Synthesis and characterization of the rheological behavior of MR fluid for polishing silicon wafer using double-disc chemical-assisted magneto-rheological finishing process. Journal of Magnetism and Magnetic Materials, 2021, 534, 168044.	2.3	18